PCN Number:	20221216013.2A	**PCN Date:**	January 24, 2023
Title:	Qualification of RFAB as an additional Fab site and additional wafer Probe site (CLARK-PR & CDAT-PR) options for select devices		
Customer Contact:	PCN Manager	**Dept:**	Quality Services
Proposed 1st Ship Date:	Jun 22, 2023	**Sample requests accepted until:**	Jan 22, 2023*

***Sample requests received after January 22, 2023 will not be supported.**

Change Type:

☐	Assembly Site	☐	Design	☐	Wafer Bump Site
☐	Assembly Process	☐	Data Sheet	☐	Wafer Bump Material
☐	Assembly Materials	☐	Part number change	☐	Wafer Bump Process
☐	Mechanical Specification	☒	Test Site	☒	Wafer Fab Site
☐	Packing/Shipping/Labeling	☐	Test Process	☒	Wafer Fab Materials
				☐	Wafer Fab Process

PCN Details

Description of Change:

Revision A is to announce the addition of a probe site change for TPD3S716QDBQRQ1 under Group 1 device that was not included on the original PCN notification. The device affected is highlighted and **bolded** in the device list below.

Texas Instruments is pleased to announce the qualification of its RFAB fabrication facility as an additional Wafer Fab source and CLARK-PR and CDAT-PR as an additional probe site options for the selected devices listed in the "Product Affected" section.

Current Fab Site			Additional Fab Site		
Current Fab Site	**Process**	**Wafer Diameter**	**Additional Fab Site**	**Process**	**Wafer Diameter**
MIHO	LBC7	200 mm	RFAB	LBC7	300 mm

Probe site changes are as follows:

Group 2 Devices:

Current Probe Site	New Probe Site
DL-MOS-4	CLARK-PR

Group 3 Devices:

Current Probe Site	New Probe Site
CLARK-PR	CDAT-PR
DL-LIN	

Test coverage, insertions, conditions will remain consistent with current testing.

Reason for Change:

Continuity of Supply

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Fab Site Information:

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
MIHO8	MH8	JPN	Ibaraki
RFAB	**RFB**	**USA**	**Richardson**

Sample product shipping label (not actual product label)

Product Affected:

Group 1 device list - MIHO adding RFAB as an additional Fab site:

SN2002036QRTERQ1	TLC59116ITPWTQ1	TPS62260QDRVRMU	TPS62290IDRVRQ1
SN55340QRTERQ1	TPD3S716QDBQRQ1	TPS62260TDDCRQ1	TPS62290TDRVRQ1
SN55340QRTETQ1	TPS55340QRTERQ1	TPS62260TDRVRQ1	TPS62293TDRVRQ1
TAS6422QDKQQ1	TPS55340QRTERWB	TPS62261TDRVRQ1	TPS62590TDRVRQ1
TAS6422QDKQRQ1	TPS55340QRTETQ1	TPS62262TDRVRQ1	
TLC59116ITPWRQ1	TPS62260IDRVRQ1	TPS62263TDRVRQ1	

Group 2 device list - MIHO adding RFAB and CLARK-PR Probe site:

TPA3110D2QPWPRQ1	TPA3111D1QPWPRQ1	TPA3112D1QPWPRQ1	**TPD3S716QDBQRQ1**

Group 3 device list - MIHO adding RFAB and CDAT-PR Probe site:

TPS54388CQRTERQ1	TPS54618CQRTERQ1	TPS57114CQRTERQ1
TPS54388QRLBRQ1	TPS57112CQRTERQ1	TPS57114QRLBRQ1
TPS54618AQRLBRQ1	TPS57112QRLBRQ1	TPS57114QRTERDN

Automotive New Product Qualification Summary
(As per AEC-Q100 and JEDEC Guidelines)

Approved 17-Jun-2020

Qualification Results
Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Spec	Min Lot Qty	SS/Lot	Test Name / Condition	Duration	Qual Device: TAS5441QPWPRQ1	QBS Process Reference: TPS2543QRTE
Test Group A – Accelerated Environment Stress Tests								
PC	A1	JEDEC J-STD-020 JESD22-A113	3	77	Automotive Preconditioning, L2	Level 2-260C	-	3/765/0
PC	A1	JEDEC J-STD-020 JESD22-A113	3	77	Automotive Preconditioning, L3	Level 3-260C	3/1258/0	-
HAST	A2	JEDEC JESD22-A110	3	77	Biased HAST 130C/85%RH	96 Hours	3/231/0	3/240/0
AC	A3	JEDEC JESD22-A102	3	77	Auto Autoclave 121C	96 Hours	3/231/0	3/231/0
TC	A4	JEDEC JESD22-A104 and Appendix 3	3	77	Temperature Cycle, -65/150C, Grade-1	500 Cycles	3/231/0	3/231/0
TC-BP	A4	MIL-STD883 Method 2011	1	30	Post Temp. Cycle Bond Pull	500 Cycles	1/30/0	1/30/0
PTC	A5	JEDEC JESD22-A105	1	45	Power Temperature Cycle, -40/125C	1000 Cycles	1/45/0	1/45/0
HTSL	A6	JEDEC JESD22-A103	1	45	High Temp Storage Bake 175C	500 Hours	3/135/0	3/135/0
Test Group B – Accelerated Lifetime Simulation Tests								
HTOL	B1	JEDEC JESD22-A108	3	77	Life Test, 125C	1000 Hours	3/231/0	-
HTOL	B1	JEDEC JESD22-A108	3	77	Life Test, 150C	408 Hours	-	3/231/0
ELFR	B2	AEC Q100-008	3	800	Early Life Failure Rate, 150C	24 Hours	-	3/2400/0
EDR	B3	AEC Q100-005	3	77	NVM Endurance, Data Retention, and Operational Life	-	N/A	-
Test Group C – Package Assembly Integrity Tests								
WBS	C1	AEC Q100-001	1	30	Wire Bond Shear (Cpk>1.67)	Wires	3/90/0	-
WBP	C2	MIL-STD883 Method 2011	1	30	Wire Bond Pull (Cpk>1.67)	Wires	3/90/0	-
SD	C3	JEDEC JESD22-B102	1	15	Surface Mount Solderability	Pb Free	1/15/0 (1)	2/30/0
SD	C3	JEDEC JESD22-B102	1	15	Surface Mount Solderability	Pb	1/15/0 (1)	-
PD	C4	JEDEC JESD22-B100 and B108	3	10	Auto Physical Dimensions	Cpk>1.67	3/30/0	3/30/0
LI	C6	JEDEC JESD22-B105	1	50	Lead Pull to Destruction	Leads	1/48/0	-
Test Group D – Die Fabrication Reliability Tests								
EM	D1	JESD61	-	-	Electromigration	-	Completed Per Process Technology Requirements	-
TDDB	D2	JESD35	-	-	Time Dependant Dielectric Breakdown	-	Completed Per Process Technology Requirements	-
HCI	D3	JESD60 & 28	-	-	Hot Injection Carrier	-	Completed Per Process Technology Requirements	-
NBTI	D4	-	-	-	Negative Bias Temperature Instability	-	Completed Per Process Technology Requirements	-
SM	D5	-	-	-	Stress Migration	-	Completed Per Process Technology Requirements	-
Test Group E – Electrical Verification Tests								
HBM	E2	AEC Q100-002	1	3	ESD - HBM - Q100	1500 V	1/3/0	-
HBM	E2	AEC Q100-002	1	3	ESD - HBM - Q100	4000 V	-	1/3/0
CDM	E3	AEC Q100-011	1	3	ESD - CDM - Q100	1000 V	1/3/0	-
CDM	E3	AEC Q100-011	1	3	ESD - CDM - Q100	1500 V	-	1/3/0
LU	E4	AEC Q100-004	1	6	Auto Latch-up	(Per AEC Q100-004)	1/6/0	1/6/0
ED	E5	AEC Q100-009	3	30	Auto Electrical Distributions	Cpk>1.67	3/90/0	3/90/0
Additional Tests								
MSL			-	-	Automotive L3 Powerpad Moisture Sensitivity	Level 3-260C	3/35/0	-
MSL			-	-	Automotive L2 Powerpad Moisture Sensitivity	Level 2-260C	-	3/35/0

- QBS: Qual By Similarity
- Qual Device TAS5441QPWPRQ1 is qualified at LEVEL3-260C

A1 (PC): Preconditioning:
Performed for THB, Biased HAST, AC, uHAST, TC & PTC samples, as applicable.

Ambient Operating Temperature by Automotive Grade Level:

Grade 0 (or E): -40°C to +150°C
Grade 1 (or Q): -40°C to +125°C
Grade 2 (or T): -40°C to +105°C
Grade 3 (or I) : -40°C to +85°C

E1 (TEST): Electrical test temperatures of Qual samples (High temperature according to Grade level):

Room/Hot/Cold: HTOL, ED
Room/Hot: THB / HAST, TC / PTC, HTSL, ELFR, ESD & LU
Room: AC/uHAST

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green
Note (1): Solderability results are from Qual ID# 20090826-9343.

Automotive New Product Qualification Summary

(As per AEC-Q100 and JEDEC Guidelines)

Approved 03/17/2015

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Spec	Min Lot Qty	SS /Lot	Test Name / Condition	Duration	Qual Device: TPS62090QRGTRQ1	Qual Device: TPS65263QRHBRQ1	Qual Device: TPS62065QDSGRQ1	QBS Process/Package: TPS2543QRTE
Test Group A - Accelerated Environment Stress Test										
HAST	A2	JESD22-A110	3	77	Biased HAST, 130C/85%RH	96 Hours	1/77/0	1/77/0	1/77/0	3/231/0
AC	A3	JESD22-A102	3	77	Autoclave 121C	96 Hours	1/77/0	1/77/0	1/77/0	3/231/0
TC-BP	A4	MIL-STD883 Method 2011	1	30	Post Temp. Cycle Bond Pull	Wires	1/30/0	1/30/0	1/30/0	1/30/0
TC	A4	JESD22-A104	3	77	Temperature Cycle, -65/150C	500 Cycles	1/77/0	1/77/0	1/77/0	3/231/0
PTC	A5	JESD22-A105	1	45	Power Temperature Cycle, -40/125C	1000 Cycles	1/45/0	1/45/0	1/45/0	1/45/0
HTSL	A6	JESD22-A103	1	45	High Temp. Storage Bake, 150C	1000 Hours	-	1/45/0	1/45/0	-
HTSL	A6	JESD22-A103	1	45	High Temp. Storage Bake, 175C	500 Hours	1/45/0	-	-	1/45/0
Test Group B - Accelerated Lifetime Simulation Test										
HTOL	B1	JESD22-A108	3	77	Life Test, 125C	1000 Hours	1/77/0	1/77/0	1/770	-
HTOL	B1	JESD22-A108	3	77	Life Test, 150C	408 Hours	-	-	-	3/231/0
ELFR	B2	AEC-Q100-008	3	800	Early Life Failure Rate, 125C	48 Hours	1/800/0	-	-	-
ELFR	B2	AEC-Q100-008	3	800	Early Life Failure Rate, 150C	24 Hours	-	-	-	3/2400/0
EDR	B3	AEC-Q100-005	3	77	NVM Endurance, Data Retention, and Operational Life	-	N/A	-	-	-
Test Group C - Package Assembly Integrity Tests										
WBS	C1	AEC-Q100-001	1	30	Bond Shear (Cpk>1.67)	Wires	1/30/0	-	1/30/0	-
WBP	C2	MIL-STD883 Method 2011	1	30	Bond Pull (Cpk>1.67	Wires	1/30/0	-	1/30/0	-
SD	C3	JESD22-B102	1	15	Surface Mount Solderability	Pb	1/15/0	-	-	-
SD	C3	JESD22-B102	1	15	Surface Mount Solderability	Pb Free	1/15/0	-	-	-
PD	C4	JESD22 B100 and B108	3	10	Physical Dimensions (Cpk>1.67)	--	3/30/0	-	-	-
Test Group D - Die Fabrication Reliability Tests										
EM	D1	JESD61	-	-	Electromigration	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
TDDB	D2	JESD35	-	-	Time Dependant Dielectric Breakdown	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
HCI	D3	JESD60 & 28	-	-	Hot Injection Carrier	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
NBTI	D4	-	-	-	Negative Bias Temperature Instability	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
SM	D5	-	-	-	Stress Migration	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
Test Group E - Electrical Verification										
HBM	E2	AEC-Q100-002	1	3	ESD - HBM	4000 V	-	1/3/0	1/3/0	1/3/0
CDM	E3	AEC-Q100-011	1	3	ESD - CDM	1500 V	-	1/3/0	1/3/0	1/3/0
LU	E4	AEC-Q100-004	1	6	Auto Latch-up	(Per AEC Q100-004)	-	1/6/0	1/6/0	1/6/0
ED	E5	AEC-Q100-009	3	30	Electrical Distributions	Cpk>1.67	-	3/90/0	3/90/0	3/90/0

- QBS: Qual By Similarity
- Qual Device TPS62090QRGTRQ1 is qualified at LEVEL2-260C

A1 (PC): Preconditioning:
Performed for THB, Biased HAST, AC, uHAST & TC samples, as applicable.

Ambient Operating Temperature by Automotive Grade Level:
Grade 0 (or E): -40C to +150C
Grade 1 (or Q): -40C to +125C
Grade 2 (or T): -40C to +105C
Grade 3 (or I) : -40C to +85C

C1/C2 (WBS / WBP):
Wire Bond Shear & Wire Bond Pull data from eQDB 20140626-106021

C4 (Physical dimensions):
Physical Dimensions data from eQDB 20140626-106021

E1 (TEST): Electrical test temperatures of Qual samples (High temperature according to Grade level):
Room/Hot/Cold : HTOL, ED
Room/Hot : THB / HAST, TC / PTC, HTSL, ELFR, ESD & LU
Room : AC/uHAST

Green/Pb-free Status:
Qualified Pb-Free (SMT) and Green

Automotive New Product Qualification Summary

(As per AEC-Q100 and JEDEC Guidelines)

Approved 24-Oct-2018

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

	Type	#	Test Spec	Min Lot Qty	SS/ Lot	Test Name / Condition	Duration	Qual Device: TPS61088QRHLQ1	QBS Process Reference: TPS2543QRTE
	Test Group A – Accelerated Environment Stress Tests								
	PC	A1	JEDEC J-STD-020 JESD22-A113	3	77	Automotive Preconditioning	Level 2-260C	3/All/0	3/All/0
	HAST	A2	JEDEC JESD22-A110	3	77	Biased HAST, 130C/85%RH	96 Hours	1/77/0	3/240/0
	AC	A3	JEDEC JESD22-A102	3	77	Autoclave 121C	96 Hours	1/77/0	3/237/0
	TC	A4	JEDEC JESD22-A104 and Appendix 3	3	77	Temperature Cycle, -65/150C	500 Cycles	3/231/0	3/238/0
	TC-BP	A4	MIL-STD883 Method 2011	1	5	Post Temp. Cycle Bond Pull	500 Cycles	1/5/0	1/5/0
	PTC	A5	JEDEC JESD22-A105	1	45	Power Temperature Cycle, -40/125C	1000 Cycles	1/45/0	1/50/0
	HTSL	A6	JEDEC JESD22-A103	1	45	High Temp. Storage Bake, 150C	1000 Hours	1/45/0	-
	HTSL	A6	JEDEC JESD22-A103	1	45	High Temp. Storage Bake, 175C	500 Hours	-	3/149/0
	Test Group B – Accelerated Lifetime Simulation Tests								
	HTOL	B1	JEDEC JESD22-A108	3	77	Life Test, 125C	1000 Hours	1/77/0	-
	HTOL	B1	JEDEC JESD22-A108	3	77	Life Test, 150C	408 Hours	-	3/231/0
	ELFR	B2	AEC Q100-008	3	800	Early Life Failure Rate, 125C	48 Hours	-	-
	ELFR	B2	AEC Q100-008	3	800	Early Life Failure Rate, 150C	24 Hours	-	3/2640/0
	EDR	B3	AEC Q100-005	3	77	NVM Endurance, Data Retention, and Operational Life	--	N/A	-

			Test Group C – Package Assembly Integrity Tests						
	WBS	C1	AEC Q100-001	1	30	Bond Shear (Cpk>1.67)	Wires	1/30/0	-
	WBP	C2	MIL-STD883 Method 2011	1	30	Bond Pull (Cpk>1.67)	Wires	1/30/0	-
	SD	C3	JEDEC JESD22-B102	1	15	Surface Mount Solderability	Pb Free	1/15/0	2/30/0
	SD	C3	JEDEC JESD22-B102	1	15	Surface Mount Solderability	Pb Solder	1/15/0	-
	PD	C4	JEDEC JESD22-B100 and B108	3	10	Physical Dimensions (Ppk>1.67)	--	3/90/0	3/90/0
	SBS	C5	AEC Q100-010	3	50	Solder Ball Shear (Cpk>1.67)	Post HTSL/Bump	N/A	-
	LI	C6	JEDEC JESD22-B105	1	50	Lead Integrity	Leads	N/A	-
			Test Group D – Die Fabrication Reliability Tests						
	EM	D1	JESD61	-	-	Electromigration	--	Completed Per Process Technology Requirements	-
	TDDB	D2	JESD35	-	-	Time Dependant Dielectric Breakdown	--	Completed Per Process Technology Requirements	-
	HCI	D3	JESD60 & 28	-	-	Hot Injection Carrier	--	Completed Per Process Technology Requirements	-
	NBTI	D4	-	-	-	Negative Bias Temperature Instability	--	Completed Per Process Technology Requirements	-
	SM	D5	-	-	-	Stress Migration	--	Completed Per Process Technology Requirements	-
			Test Group E – Electrical Verification Tests						
	HBM	E2	AEC Q100-002	1	3	ESD - HBM	2500 V	1/3/0	1/3/0
	CDM	E3	AEC Q100-011	1	3	ESD - CDM	1000 V	1/3/0	1/3/0
	LU	E4	AEC Q100-004	1	6	Latch-up	(Per AEC Q100-004)	1/6/0	1/6/0
	ED	E5	AEC Q100-009	3	30	Electrical Distributions	Cpk>1.67 Room, Hot, & Cold	3/90/0	3/90/0

- QBS: Qual By Similarity
- Qual Device TPS61088QRHLQ1 is qualified at LEVEL2-260C

A1 (PC): Preconditioning:

Performed for THB, Biased HAST, AC, uHAST, TC & PTC samples, as applicable.

Ambient Operating Temperature by Automotive Grade Level:

Grade 0 (or E): -40°C to +150°C
Grade 1 (or Q): -40°C to +125°C
Grade 2 (or T): -40°C to +105°C
Grade 3 (or I) : -40°C to +85°C

E1 (TEST): Electrical test temperatures of Qual samples (High temperature according to Grade level):

Room/Hot/Cold : HTOL, ED
Room/Hot : THB / HAST, TC / PTC, HTSL, ELFR, ESD & LU
Room : AC/uHAST

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

Automotive New Product Qualification Summary

(As per AEC-Q100 and JEDEC Guidelines)

Approve Date 10-July-2018

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

	Type	#	Test Spec	Min Lot Qty	SS/ Lot	Test Name / Condition	Duration	Qual Device: TLC6C5724QDAPRQ1	Qual Device: TLC6C5712QPWPRQ1	QBS Process Reference: TPS2543QRTE
Test Group A – Accelerated Environment Stress Tests										
	PC	A1	JEDEC J-STD-020 JESD22-A113	-	-	Automotive Preconditioning	Level 2-260C	-	-	3/765/0
	PC	A1	JEDEC J-STD-020 JESD22-A113	-	-	Automotive Preconditioning	Level 3-260C	3/738/0	3/738/0	-
	HAST	A2	JEDEC JESD22-A110	1	77	Biased HAST, 130C/85%RH	96 Hours	3/231/0	3/231/0	3/231/0
	AC	A3	JEDEC JESD22-A102	1	77	Autoclave 121C	96 Hours	3/231/0	3/231/0	3/231/0
	TC	A4	JEDEC JESD22-A104 and Appendix 3	1	77	Temperature Cycle, -65/150C	500 Cycles	3/231/0	3/231/0	3/231/0
	TC-BP	A4	MIL-STD883 Method 2011	1	5	Post Temp. Cycle Bond Pull	per MIL-STD 883 Method 2011	1/5/0	-	1/5/0
	PTC	A5	JEDEC JESD22-A105	1	45	Power Temperature Cycle, -40/125C	1000 Cycles	1/45/0	-	1/45/0
	HTSL	A6	JEDEC JESD22-A103	1	77	High Temp. Storage Bake, 150C	1000 Hours	1/77/0	-	-
	HTSL	A6	JEDEC JESD22-A103	1	45	High Temp. Storage Bake, 175C	500 Hours	-	1/45/0	3/135/0
Test Group B – Accelerated Lifetime Simulation Tests										
	HTOL	B1	JEDEC JESD22-A108	1	77	Life Test, 150C	408 Hours	1/77/0	3/231/0	-
	HTOL	B1	JEDEC JESD22-A108	3	77	Life Test, 125C	1000 Hours	-	-	3/231/0
	ELFR	B2	AEC Q100-008	3	800	Early Life Failure Rate, 150C	24 Hours	-	3/2400/0	3/2240/0
	ELFR	B2	AEC Q100-008	3	800	Early Life Failure Rate, 125C	48 Hours	-	-	-
Test Group C – Package Assembly Integrity Tests										
	WBS	C1	AEC Q100-001	1	30	Bond Shear (Cpk>1.67)	Wires	3/90/0	-	-
	WBP	C2	MIL-STD883 Method 2011	1	30	Bond Pull (Cpk>1.67)	Wires	3/90/0	-	-
	SD	C3	JEDEC JESD22-B102	1	15	Surface Mount Solderability >95% Lead Coverage	8 Hours Steam Age, Pb	-	-	1/15/0
	SD	C3	JEDEC JESD22-B102	1	15	Surface Mount Solderability >95% Lead Coverage	8 Hours Steam Age, Pb Free	1/22/0	-	1/15/0
	PD	C4	JEDEC JESD22-B100 and B108	3	10	Physical Dimensions (Cpk>1.67)	--	3/30/0	-	3/30/0
Test Group D – Die Fabrication Reliability Tests										
	EM	D1	JESD61	-	-	Electromigration	--	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
	TDDB	D2	JESD35	-	-	Time Dependent Dielectric Breakdown	--	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
	HCI	D3	JESD60 & 28	-	-	Hot Injection Carrier	--	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
	NBTI	D4	-	-	-	Negative Bias Temperature Instability	--	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
	SM	D5	-	-	-	Stress Migration	--	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
Test Group E – Electrical Verification Tests										
	HBM	E2	AEC Q100-002	1	3	ESD - HBM	2000 V	1/3/0	1/3/0	1/3/0
	HBM	E2	AEC Q100-002	1	3	ESD - HBM	4000 V	-	1/3/0	-
	CDM	E3	AEC Q100-011	1	3	ESD - CDM	500 V	1/3/0	-	-
	CDM	E3	AEC Q100-011	1	3	ESD - CDM	750 V	1/3/0	1/3/0	-
	CDM	E3	AEC Q100-011	1	3	ESD - CDM	1000 V	-	1/3/0	1/3/0
	LU	E4	AEC Q100-004	1	6	Latch-up	(Per AEC Q100-004)	1/6/0	1/6/0	1/6/0
	ED	E5	AEC Q100-009	3	30	Electrical Distributions	Cpk>1.67 Room, hot, and cold test	3/90/0	3/90/0	3/90/0

- Qual Device TLC6C5724QDAPRQ1 is qualified at LEVEL3-260C

A1 (PC): Preconditioning:
Performed for THB, Biased HAST, AC, uHAST &TC samples, as applicable.

Junction Operating Temperature by Automotive Grade Level:
Grade 0 (or E): -40°C to +150°C
Grade 1 (or Q): -40°C to +125°C
Grade 2 (or T): -40°C to +105°C
Grade 3 (or I): -40°C to +85°C

E1 (TEST): Electrical test temperatures of Qual samples (High temperature according to Grade level):
Room/Hot/Cold : HTOL, ED
Room/Hot : THB / HAST, TC / PTC, HTSL, ELFR, ESD & LU
Room : AC/uHAST

Green/Pb-free Status:
Qualified Pb-Free (SMT) and Green

For questions regarding this notice, e-mails can be sent to the contact below or your local Field Sales Representative.

Location	E-Mail
WW Change Management Team	PCN_ww_admin_team@list.ti.com

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